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METHOD OF FORMING LAMINATED WIRING
NORITAKE CO LTD; NORITAKE DENSHI KOGYO KK

Inventor(s):

HOSOMI KAZUNORI
MORI SHINSUKE

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Abstract:

PROBLEM TO BE SOLVED: To provide a method of forming a laminated wiring having no short- circuit defects.

SOLUTION: This method of forming a laminated wiring having row wirings formed on column wirings 32 and an insulation layer 36 comprises a first printing step of printing a thick-film paste to form a first printed film layer 52, a drying step of drying this layer 52 as a dry film 54, an inspecting step of inspecting the electrical insulation from the column wirings 32 to locate short circuits 58 between the dry film 54 and the column wirings 32, a dry film removing step of locally removing the dry film 54 to expose the column wirings 32 at the short circuits 58, a repairing step of coating a thick film insulation paste on the exposed parts to repair, and a second printing step of coating the thick film Ag paste thereon. Thus, the short circuits 58 are located with the thick film Ag paste being dry for forming the row wirings, and the dry film 54 thereat is removed locally to repair the short circuit defects.